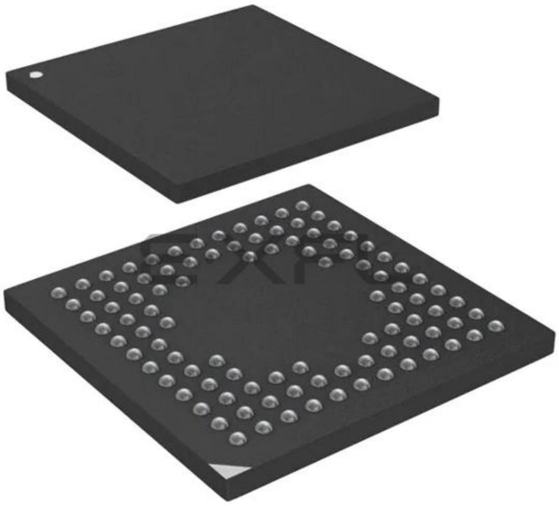

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M3
Core Size	32-Bit Single-Core
Speed	32MHz
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART, USB
Peripherals	Brown-out Detect/Reset, Cap Sense, DMA, I²S, LCD, POR, PWM, WDT
Number of I/O	83
Program Memory Size	256KB (256K x 8)
Program Memory Type	FLASH
EEPROM Size	8K x 8
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 25x12b; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-UFBGA
Supplier Device Package	100-UFBGA (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/stmicroelectronics/stm32l152vch6

2.1 Device overview

Table 2. Ultra-low-power STM32L151xC and STM32L152xC device features and peripheral counts

Peripheral		STM32L15xCC	STM32L15xUC STM32L15xRC	STM32L15xVC
Flash (Kbytes)		256		
Data EEPROM (Kbytes)		8		
RAM (Kbytes)		32		
Timers	32 bit	1		
	General-purpose	6		
	Basic	2		
Communication interfaces	SPI	8(3)[1]		
	I^2S	2		
	I^2C	2		
	USART	3		
	USB	1		
GPIOs		37	51	83
Operation amplifiers		2		
12-bit synchronized ADC Number of channels		1 14	1 21	1 25
12-bit DAC Number of channels		2 2		
LCD [2] COM x SEG		1 4x18	1 4x32 or 8x28	1 4x44 or 8x40
Comparators		2		
Capacitive sensing channels		16	23	
Max. CPU frequency		32 MHz		
Operating voltage		1.8 V to 3.6 V (down to 1.65 V at power-down) with BOR option 1.65 V to 3.6 V without BOR option		
Operating temperatures		Ambient operating temperature: -40 °C to 85 °C / -40 °C to 105 °C Junction temperature: –40 to + 110 °C		
Packages		LQFP48, UFQFPN48	LQFP64, WLCSP63	LQFP100, UFBGA100

1. 5 SPIs are USART configured in synchronous mode emulating SPI master.
2. STM32L152xx devices only.

Table 3. Functionalities depending on the operating power supply range (continued)

	Functionalities depending on the operating power supply range			
Operating power supply range	**DAC and ADC operation**	**USB**	**Dynamic voltage scaling range**	**I/O operation**
V_{DD}=V_{DDA} = 2.0 to 2.4 V	Conversion time up to 500 Ksps	Functional(2)	Range 1, Range 2 or Range 3	Full speed operation
V_{DD}=V_{DDA} = 2.4 to 3.6 V	Conversion time up to 1 Msps	Functional(2)	Range 1, Range 2 or Range 3	Full speed operation

1. CPU frequency changes from initial to final must respect "F_{CPU} initial < 4*F_{CPU} final" to limit V_{CORE} drop due to current consumption peak when frequency increases. It must also respect 5 µs delay between two changes. For example to switch from 4.2 MHz to 32 MHz, the user can switch from 4.2 MHz to 16 MHz, wait 5 µs, then switch from 16 MHz to 32 MHz.
2. Should be USB compliant from I/O voltage standpoint, the minimum V_{DD} is 3.0 V.

Table 4. CPU frequency range depending on dynamic voltage scaling

CPU frequency range	Dynamic voltage scaling range
16 MHz to 32 MHz (1ws) 32 kHz to 16 MHz (0ws)	Range 1
8 MHz to 16 MHz (1ws) 32 kHz to 8 MHz (0ws)	Range 2
2.1MHz to 4.2 MHz (1ws) 32 kHz to 2.1 MHz (0ws)	Range 3

3.5 Low-power real-time clock and backup registers

The real-time clock (RTC) is an independent BCD timer/counter. Dedicated registers contain the sub-second, second, minute, hour (12/24 hour), week day, date, month, year, in BCD (binary-coded decimal) format. Correction for 28, 29 (leap year), 30, and 31 day of the month are made automatically. The RTC provides two programmable alarms and programmable periodic interrupts with wakeup from Stop and Standby modes.

The programmable wakeup time ranges from 120 µs to 36 hours.

The RTC can be calibrated with an external 512 Hz output, and a digital compensation circuit helps reduce drift due to crystal deviation.

The RTC can also be automatically corrected with a 50/60Hz stable powerline.

The RTC calendar can be updated on the fly down to sub second precision, which enables network system synchronization.

A time stamp can record an external event occurrence, and generates an interrupt.

There are thirty-two 32-bit backup registers provided to store 128 bytes of user application data. They are cleared in case of tamper detection.

Three pins can be used to detect tamper events. A change on one of these pins can reset backup register and generate an interrupt. To prevent false tamper event, like ESD event, these three tamper inputs can be digitally filtered.

3.6 GPIOs (general-purpose inputs/outputs)

Each of the GPIO pins can be configured by software as output (push-pull or open-drain), as input (with or without pull-up or pull-down) or as peripheral alternate function. Most of the GPIO pins are shared with digital or analog alternate functions, and can be individually remapped using dedicated AFIO registers. All GPIOs are high current capable. The alternate function configuration of I/Os can be locked if needed following a specific sequence in order to avoid spurious writing to the I/O registers. The I/O controller is connected to the AHB with a toggling speed of up to 16 MHz.

External interrupt/event controller (EXTI)

The external interrupt/event controller consists of 24 edge detector lines used to generate interrupt/event requests. Each line can be individually configured to select the trigger event (rising edge, falling edge, both) and can be masked independently. A pending register maintains the status of the interrupt requests. The EXTI can detect an external line with a pulse width shorter than the Internal APB2 clock period. Up to 83 GPIOs can be connected to the 16 external interrupt lines. The 8 other lines are connected to RTC, PVD, USB, comparator events or capacitive sensing acquisition.

3.7 Memories

The STM32L151xC and STM32L152xC devices have the following features:

- 32 Kbytes of embedded RAM accessed (read/write) at CPU clock speed with 0 wait states. With the enhanced bus matrix, operating the RAM does not lead to any performance penalty during accesses to the system bus (AHB and APB buses).
- The non-volatile memory is divided into three arrays:
  – 256 Kbytes of embedded Flash program memory
  – 8 Kbytes of data EEPROM
  – Options bytes

  The options bytes are used to write-protect or read-out protect the memory (with 4 Kbytes granularity) and/or readout-protect the whole memory with the following options:
  – Level 0: no readout protection
  – Level 1: memory readout protection, the Flash memory cannot be read from or written to if either debug features are connected or boot in RAM is selected
  – Level 2: chip readout protection, debug features (ARM Cortex-M3 JTAG and serial wire) and boot in RAM selection disabled (JTAG fuse)

  The whole non-volatile memory embeds the error correction code (ECC) feature.

  The user area of the Flash memory can be protected against Dbus read access by PCROP feature (see RM0038 for details).

3.8 DMA (direct memory access)

The flexible 12-channel, general-purpose DMA is able to manage memory-to-memory, peripheral-to-memory and memory-to-peripheral transfers. The DMA controller supports circular buffer management, avoiding the generation of interrupts when the controller reaches the end of the buffer.

Each channel is connected to dedicated hardware DMA requests, with software trigger support for each channel. Configuration is done by software and transfer sizes between source and destination are independent.

The DMA can be used with the main peripherals: SPI, I^2C, USART, general-purpose timers, DAC and ADC.

TIM2, TIM3, TIM4, TIM5 all have independent DMA request generation.

These timers are capable of handling quadrature (incremental) encoder signals and the digital outputs from 1 to 3 hall-effect sensors.

TIM10, TIM11 and TIM9

TIM10 and TIM11 are based on a 16-bit auto-reload upcounter. TIM9 is based on a 16-bit auto-reload up/down counter. They include a 16-bit prescaler. TIM10 and TIM11 feature one independent channel, whereas TIM9 has two independent channels for input capture/output compare, PWM or one-pulse mode output. They can be synchronized with the TIM2, TIM3, TIM4, TIM5 full-featured general-purpose timers.

They can also be used as simple time bases and be clocked by the LSE clock source (32.768 kHz) to provide time bases independent from the main CPU clock.

3.16.2 Basic timers (TIM6 and TIM7)

These timers are mainly used for DAC trigger generation. They can also be used as generic 16-bit time bases.

3.16.3 SysTick timer

This timer is dedicated to the OS, but could also be used as a standard downcounter. It is based on a 24-bit downcounter with autoreload capability and a programmable clock source. It features a maskable system interrupt generation when the counter reaches 0.

3.16.4 Independent watchdog (IWDG)

The independent watchdog is based on a 12-bit downcounter and 8-bit prescaler. It is clocked from an independent 37 kHz internal RC and, as it operates independently of the main clock, it can operate in Stop and Standby modes. It can be used either as a watchdog to reset the device when a problem occurs, or as a free-running timer for application timeout management. It is hardware- or software-configurable through the option bytes. The counter can be frozen in debug mode.

3.16.5 Window watchdog (WWDG)

The window watchdog is based on a 7-bit downcounter that can be set as free-running. It can be used as a watchdog to reset the device when a problem occurs. It is clocked from the main clock. It has an early warning interrupt capability and the counter can be frozen in debug mode.

3.17 Communication interfaces

3.17.1 I²C bus

Up to two I²C bus interfaces can operate in multimaster and slave modes. They can support standard and fast modes.

They support dual slave addressing (7-bit only) and both 7- and 10-bit addressing in master mode. A hardware CRC generation/verification is embedded.

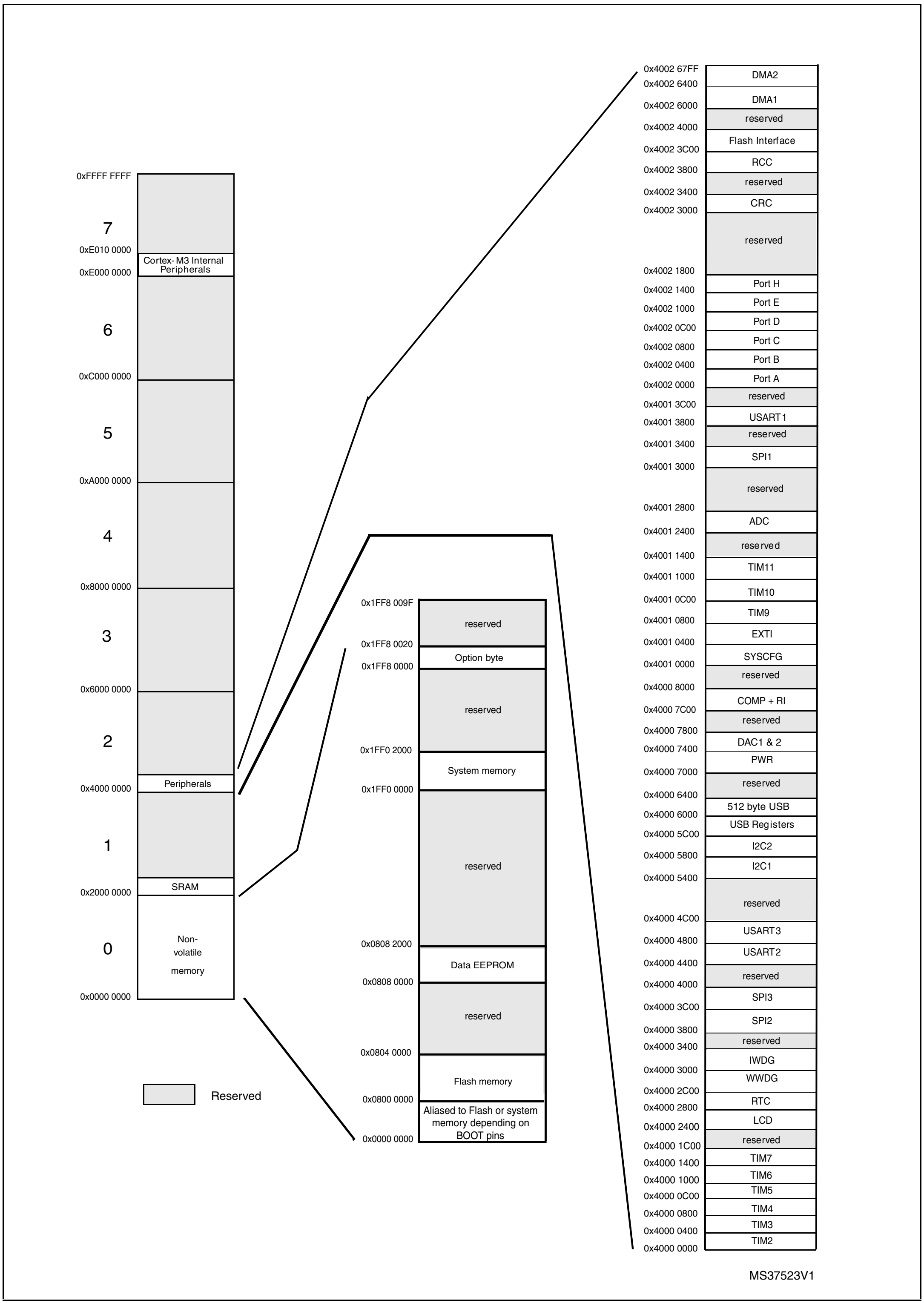
They can be served by DMA and they support SM Bus 2.0/PM Bus.

Table 9. STM32L151xC and STM32L152xC pin definitions (continued)

Pins					Pin name	Pin type(1)	I / O Structure	Main function(2) (after reset)	Pin functions	
UFBGA100	LQFP100	LQFP64	WLCSP63	LQFP48 or UFQFPN48					Alternate functions	Additional functions
C10	79	52	A3	-	PC11	I/O	FT	PC11	SPI3_MISO/ USART3_RX/ LCD_SEG29/ LCD_SEG41/ LCD_COM5	-
B10	80	53	B4	-	PC12	I/O	FT	PC12	SPI3_MOSI/I2S3_SD/ USART3_CK/ LCD_SEG30/ LCD_SEG42/ LCD_COM6	-
C9	81	-	-	-	PD0	I/O	FT	PD0	TIM9_CH1/SPI2_NSS/ I2S2_WS	-
B9	82	-	-	-	PD1	I/O	FT	PD1	SPI2_SCK/I2S2_CK	-
C8	83	54	A4	-	PD2	I/O	FT	PD2	TIM3_ETR/LCD_SEG31 /LCD_SEG43/ LCD_COM7	-
B8	84	-	-	-	PD3	I/O	FT	PD3	SPI2_MISO/ USART2_CTS	-
B7	85	-	-	-	PD4	I/O	FT	PD4	SPI2_MOSI/I2S2_SD/ USART2_RTS	-
A6	86	-		-	PD5	I/O	FT	PD5	USART2_TX	-
B6	87	-	-	-	PD6	I/O	FT	PD6	USART2_RX	-
A5	88	-	-	-	PD7	I/O	FT	PD7	TIM9_CH2/USART2_CK	-
A8	89	55	C4	39	PB3	I/O	FT	JTDO	TIM2_CH2/SPI1_SCK/ SPI3_SCK/I2S3_CK/ LCD_SEG7/JTDO	COMP2_INM
A7	90	56	D4	40	PB4	I/O	FT	NJTRST	TIM3_CH1/SPI1_MISO/ SPI3_MISO/LCD_SEG8 /NJTRST	COMP2_INP
C5	91	57	A5	41	PB5	I/O	FT	PB5	TIM3_CH2/I2C1_SMBA/ SPI1_MOSI/SPI3_MOSI /I2S3_SD/LCD_SEG9	COMP2_INP

5 Memory mapping

Figure 9. Memory map



6.2 Absolute maximum ratings

Stresses above the absolute maximum ratings listed in *Table 11: Voltage characteristics*, *Table 12: Current characteristics*, and *Table 13: Thermal characteristics* may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these conditions is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

Table 11. Voltage characteristics

Symbol	Ratings	Min	Max	Unit
$V_{DD}–V_{SS}$	External main supply voltage (including V_{DDA} and V_{DD})(1)	–0.3	4.0	V
V_{IN}(2)	Input voltage on five-volt tolerant pin	V_{SS} –0.3	V_{DD}+4.0	
	Input voltage on any other pin	V_{SS} –0.3	4.0	
$\|\Delta V_{DDx}\|$	Variations between different V_{DD} power pins	-	50	mV
$\|V_{SSX} – V_{SS}\|$	Variations between all different ground pins(3)	-	50	
$V_{REF+} – V_{DDA}$	Allowed voltage difference for $V_{REF+} > V_{DDA}$	-	0.4	V
$V_{ESD(HBM)}$	Electrostatic discharge voltage (human body model)	see *Section 6.3.11*		

1. All main power (V_{DD}, V_{DDA}) and ground (V_{SS}, V_{SSA}) pins must always be connected to the external power supply, in the permitted range.
2. V_{IN} maximum must always be respected. Refer to *Table 12* for maximum allowed injected current values.
3. Include V_{REF-} pin.

Table 12. Current characteristics

Symbol	Ratings	Max.	Unit
$I_{VDD(\Sigma)}$	Total current into sum of all V_{DD_x} power lines (source)(1)	100	mA
$I_{VSS(\Sigma)}$(2)	Total current out of sum of all V_{SS_x} ground lines (sink)(1)	100	
$I_{VDD(PIN)}$	Maximum current into each V_{DD_x} power pin (source)(1)	70	
$I_{VSS(PIN)}$	Maximum current out of each VSS_x ground pin (sink)(1)	-70	
I_{IO}	Output current sunk by any I/O and control pin	25	
	Output current sourced by any I/O and control pin	- 25	
$\Sigma I_{IO(PIN)}$	Total output current sunk by sum of all IOs and control pins(2)	60	
	Total output current sourced by sum of all IOs and control pins(2)	-60	
$I_{INJ(PIN)}$ (3)	Injected current on five-volt tolerant I/O(4), RST and B pins	-5/+0	
	Injected current on any other pin (5)	± 5	
$\Sigma I_{INJ(PIN)}$	Total injected current (sum of all I/O and control pins)(6)	± 25	

1. All main power (V_{DD}, V_{DDA}) and ground (V_{SS}, V_{SSA}) pins must always be connected to the external power supply, in the permitted range.
2. This current consumption must be correctly distributed over all I/Os and control pins. The total output current must not be sunk/sourced between two consecutive power supply pins referring to high pin count LQFP packages.
3. Negative injection disturbs the analog performance of the device. See note in *Section 6.3.17*.

Table 18. Current consumption in Run mode, code with data processing running from Flash

Symbol	Parameter	Conditions		f_{HCLK}	Typ	Max[1]	Unit
I_{DD} (Run from Flash)	Supply current in Run mode, code executed from Flash	$f_{HSE} = f_{HCLK}$ up to 16 MHz included, $f_{HSE} = f_{HCLK}/2$ above 16 MHz (PLL ON)[2]	Range 3, V_{CORE}=1.2 V VOS[1:0] = 11	1 MHz	215	400	µA
				2 MHz	400	600	
				4 MHz	725	960	
			Range 2, V_{CORE}=1.5 V VOS[1:0] = 10	4 MHz	0.915	1.1	mA
				8 MHz	1.75	2.1	
				16 MHz	3.4	3.9	
			Range 1, V_{CORE}=1.8 V VOS[1:0] = 01	8 MHz	2.1	2.8	
				16 MHz	4.2	4.9	
				32 MHz	8.25	9.4	
		HSI clock source (16 MHz)	Range 2, V_{CORE}=1.5 V VOS[1:0] = 10	16 MHz	3.5	4	
			Range 1, V_{CORE}=1.8 V VOS[1:0] = 01	32 MHz	8.2	9.6	
		MSI clock, 65 kHz	Range 3, V_{CORE}=1.2 V VOS[1:0] = 11	65 kHz	40.5	110	µA
		MSI clock, 524 kHz		524 kHz	125	190	
		MSI clock, 4.2 MHz		4.2 MHz	775	900	

1. Guaranteed by characterization results, unless otherwise specified.
2. Oscillator bypassed (HSEBYP = 1 in RCC_CR register).

Table 24. Typical and maximum current consumptions in Standby mode

Symbol	Parameter	Conditions		Typ	Max(1)	Unit
I_{DD} (Standby with RTC)	Supply current in Standby mode with RTC enabled	RTC clocked by LSI (no independent watchdog)	T_A = -40 °C to 25 °C V_{DD} = 1.8 V	0.905	-	µA
			T_A = -40 °C to 25 °C	1.15	1.9	
			T_A = 55 °C	1.5	2.2	
			T_A= 85 °C	1.75	4	
			T_A = 105 °C	2.1	8.3(2)	
		RTC clocked by LSE external quartz (no independent watchdog)(3)	T_A = -40 °C to 25 °C V_{DD} = 1.8 V	0.98	-	
			T_A = -40 °C to 25 °C	1.3	-	
			T_A = 55 °C	1.7	-	
			T_A= 85 °C	2.05	-	
			T_A = 105 °C	2.45	-	
I_{DD} (Standby)	Supply current in Standby mode (RTC disabled)	Independent watchdog and LSI enabled	T_A = -40 °C to 25 °C	1	1.7	
		Independent watchdog and LSI OFF	T_A = -40 °C to 25 °C	0.29	0.6	
			T_A = 55 °C	0.345	0.9	
			T_A = 85 °C	0.575	2.75	
			T_A = 105 °C	1.45	7(2)	
I_{DD} (WU from Standby)	Supply current during wakeup time from Standby mode	-	T_A = -40 °C to 25 °C	1	-	mA

1. Guaranteed by characterization results, unless otherwise specified.
2. Guaranteed by test in production.
3. Based on characterization done with a 32.768 kHz crystal (MC306-G-06Q-32.768, manufacturer JFVNY) with two 6.8pF loading capacitors.

On-chip peripheral current consumption

The current consumption of the on-chip peripherals is given in the following table. The MCU is placed under the following conditions:

- all I/O pins are in input mode with a static value at V_{DD} or V_{SS} (no load)
- all peripherals are disabled unless otherwise mentioned
- the given value is calculated by measuring the current consumption
  – with all peripherals clocked off
  – with only one peripheral clocked on

Multi-speed internal (MSI) RC oscillator

Table 33. MSI oscillator characteristics

Symbol	Parameter	Condition	Typ	Max	Unit
f_{MSI}	Frequency after factory calibration, done at V_{DD}= 3.3 V and T_A = 25 °C	MSI range 0	65.5	-	kHz
		MSI range 1	131	-	
		MSI range 2	262	-	
		MSI range 3	524	-	
		MSI range 4	1.05	-	MHz
		MSI range 5	2.1	-	
		MSI range 6	4.2	-	
ACC_{MSI}	Frequency error after factory calibration	-	±0.5	-	%
$D_{TEMP(MSI)}$[1]	MSI oscillator frequency drift 0 °C ≤ T_A ≤ 105 °C	-	±3	-	%
$D_{VOLT(MSI)}$[1]	MSI oscillator frequency drift 1.65 V ≤ V_{DD} ≤ 3.6 V, T_A = 25 °C	-	-	2.5	%/V
$I_{DD(MSI)}$[2]	MSI oscillator power consumption	MSI range 0	0.75	-	µA
		MSI range 1	1	-	
		MSI range 2	1.5	-	
		MSI range 3	2.5	-	
		MSI range 4	4.5	-	
		MSI range 5	8	-	
		MSI range 6	15	-	
$t_{SU(MSI)}$	MSI oscillator startup time	MSI range 0	30	-	µs
		MSI range 1	20	-	
		MSI range 2	15	-	
		MSI range 3	10	-	
		MSI range 4	6	-	
		MSI range 5	5	-	
		MSI range 6, Voltage range 1 and 2	3.5	-	
		MSI range 6, Voltage range 3	5	-	

Output driving current

The GPIOs (general purpose input/outputs) can sink or source up to ±8 mA, and sink or source up to ±20 mA with the non-standard V_{OL}/V_{OH} specifications given in Table 44.

In the user application, the number of I/O pins which can drive current must be limited to respect the absolute maximum rating specified in Section 6.2:

- The sum of the currents sourced by all the I/Os on $V_{DD,}$ plus the maximum Run consumption of the MCU sourced on $V_{DD,}$ cannot exceed the absolute maximum rating $I_{VDD(\Sigma)}$ (see Table 12).
- The sum of the currents sunk by all the I/Os on V_{SS} plus the maximum Run consumption of the MCU sunk on V_{SS} cannot exceed the absolute maximum rating $I_{VSS(\Sigma)}$ (see Table 12).

Output voltage levels

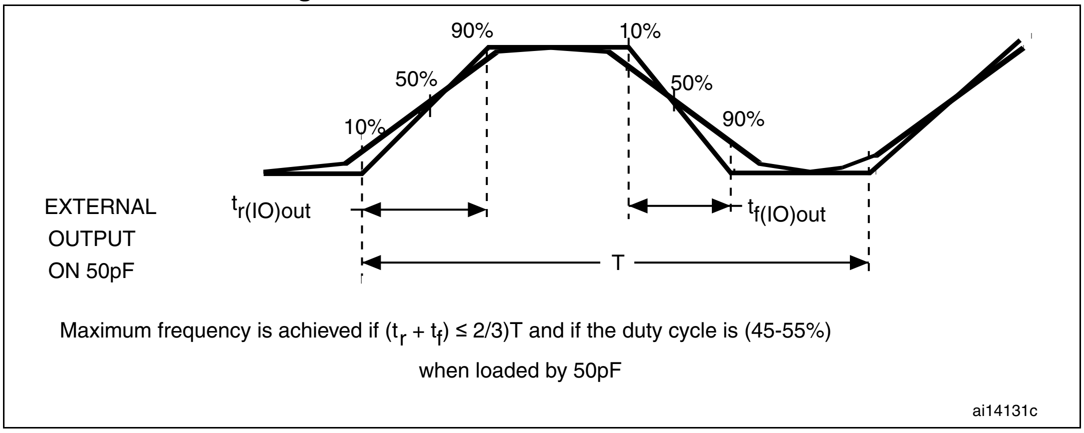
Unless otherwise specified, the parameters given in Table 44 are derived from tests performed under the conditions summarized in Table 14. All I/Os are CMOS and TTL compliant.

Table 44. Output voltage characteristics

Symbol	Parameter	Conditions	Min	Max	Unit
V_{OL} (1)(2)	Output low level voltage for an I/O pin	I_{IO} = 8 mA 2.7 V < V_{DD} < 3.6 V	-	0.4	V
V_{OH} (2)(3)	Output high level voltage for an I/O pin		V_{DD}-0.4	-	
V_{OL} (3)(4)	Output low level voltage for an I/O pin	I_{IO} = 4 mA 1.65 V < V_{DD} < 3.6 V	-	0.45	
V_{OH} (3)(4)	Output high level voltage for an I/O pin		V_{DD}-0.45	-	
V_{OL} (1)(4)	Output low level voltage for an I/O pin	I_{IO} = 20 mA 2.7 V < V_{DD} < 3.6 V	-	1.3	
V_{OH} (3)(4)	Output high level voltage for an I/O pin		V_{DD}-1.3	-	

1. The I_{IO} current sunk by the device must always respect the absolute maximum rating specified in Table 12 and the sum of I_{IO} (I/O ports and control pins) must not exceed I_{VSS}.
2. Guaranteed by test in production.
3. The I_{IO} current sourced by the device must always respect the absolute maximum rating specified in Table 12 and the sum of I_{IO} (I/O ports and control pins) must not exceed I_{VDD}.
4. Guaranteed by characterization results.

Figure 19. I/O AC characteristics definition



6.3.14 NRST pin characteristics

The NRST pin input driver uses CMOS technology. It is connected to a permanent pull-up resistor, R_{PU} (see *Table 46*)

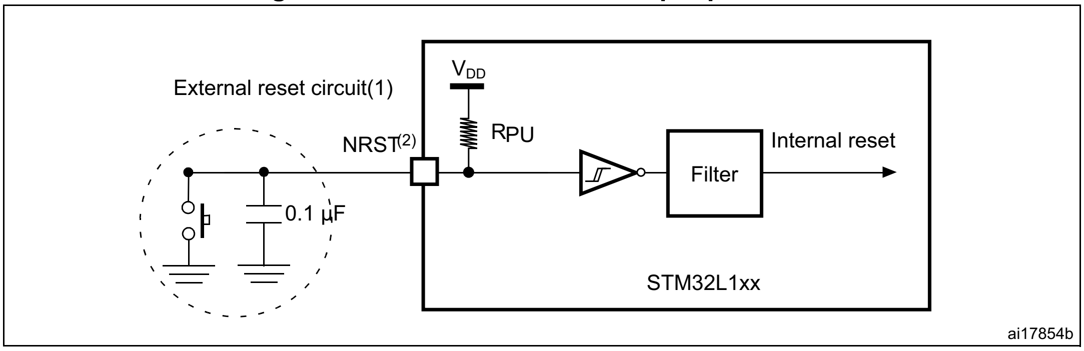
Unless otherwise specified, the parameters given in *Table 46* are derived from tests performed under the conditions summarized in *Table 14*.

Table 46. NRST pin characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{IL(NRST)}$(1)	NRST input low level voltage	-	-	-	0.3 V_{DD}	V
$V_{IH(NRST)}$(1)	NRST input high level voltage	-	$0.39V_{DD}+0.59$	-	-	
$V_{OL(NRST)}$(1)	NRST output low level voltage	I_{OL} = 2 mA 2.7 V < V_{DD} < 3.6 V	-	-	0.4	
		I_{OL} = 1.5 mA 1.65 V < V_{DD} < 2.7 V	-	-		
$V_{hys(NRST)}$(1)	NRST Schmitt trigger voltage hysteresis	-	-	$10\%V_{DD}$(2)	-	mV
R_{PU}	Weak pull-up equivalent resistor(3)	$V_{IN} = V_{SS}$	30	45	60	kΩ
$V_{F(NRST)}$(1)	NRST input filtered pulse	-	-	-	50	ns
$V_{NF(NRST)}$(3)	NRST input not filtered pulse	-	350	-	-	ns

1. Guaranteed by design.
2. With a minimum of 200 mV.
3. The pull-up is designed with a true resistance in series with a switchable PMOS. This PMOS contribution to the series resistance is around 10%.

Figure 20. Recommended NRST pin protection



1. The reset network protects the device against parasitic resets.
2. The user must ensure that the level on the NRST pin can go below the $V_{IL(NRST)}$ max level specified in *Table 46*. Otherwise the reset will not be taken into account by the device.

6.3.15 TIM timer characteristics

The parameters given in the *Table 47* are guaranteed by design.

Refer to *Section 6.3.13: I/O port characteristics* for details on the input/output ction characteristics (output compare, input capture, external clock, PWM output).

Table 47. TIMx(1) characteristics

Symbol	Parameter	Conditions	Min	Max	Unit
$t_{res(TIM)}$	Timer resolution time	-	1	-	$t_{TIMxCLK}$
		$f_{TIMxCLK}$ = 32 MHz	31.25	-	ns
f_{EXT}	Timer external clock frequency on CH1 to CH4	-	0	$f_{TIMxCLK}/2$	MHz
		$f_{TIMxCLK}$ = 32 MHz	0	16	MHz
Res_{TIM}	Timer resolution	-		16	bit
$t_{COUNTER}$	16-bit counter clock period when internal clock is selected (timer's prescaler disabled)	-	1	65536	$t_{TIMxCLK}$
		$f_{TIMxCLK}$ = 32 MHz	0.0312	2048	µs
t_{MAX_COUNT}	Maximum possible count	-	-	65536 × 65536	$t_{TIMxCLK}$
		$f_{TIMxCLK}$ = 32 MHz	-	134.2	s

1. TIMx is used as a general term to refer to the TIM2, TIM3 and TIM4 timers.

USB characteristics

The USB interface is USB-IF certified (full speed).

Table 51. USB startup time

Symbol	Parameter	Max	Unit
$t_{STARTUP}$(1)	USB transceiver startup time	1	µs

1. Guaranteed by design.

Table 52. USB DC electrical characteristics

Symbol	Parameter	Conditions	Min.(1)	Max.(1)	Unit
Input levels					
V_{DD}	USB operating voltage	-	3.0	3.6	V
V_{DI}(2)	Differential input sensitivity	I(USB_DP, USB_DM)	0.2	-	V
V_{CM}(2)	Differential common mode range	Includes V_{DI} range	0.8	2.5	
V_{SE}(2)	Single ended receiver threshold	-	1.3	2.0	
Output levels					
V_{OL}(3)	Static output level low	R_L of 1.5 kΩ to 3.6 V(4)	-	0.3	V
V_{OH}(3)	Static output level high	R_L of 15 kΩ to V_{SS}(4)	2.8	3.6	

1. All the voltages are measured from the local ground potential.
2. Guaranteed by characterization results.
3. Guaranteed by test in production.
4. R_L is the load connected on the USB drivers.

Figure 25. USB timings: definition of data signal rise and fall time

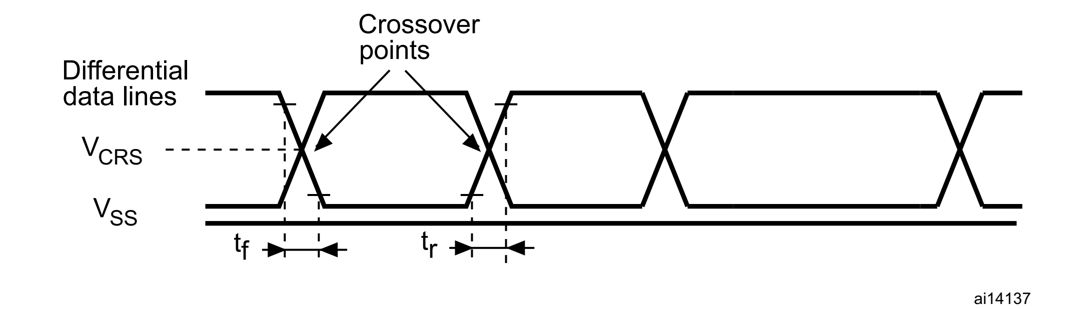


Table 53. USB: full speed electrical characteristics

Driver characteristics(1)					
Symbol	**Parameter**	**Conditions**	**Min**	**Max**	**Unit**
t_r	Rise time(2)	C_L = 50 pF	4	20	ns
t_f	Fall Time(2)	C_L = 50 pF	4	20	ns

Figure 30. Maximum dynamic current consumption on V_{REF+} supply pin during ADC conversion

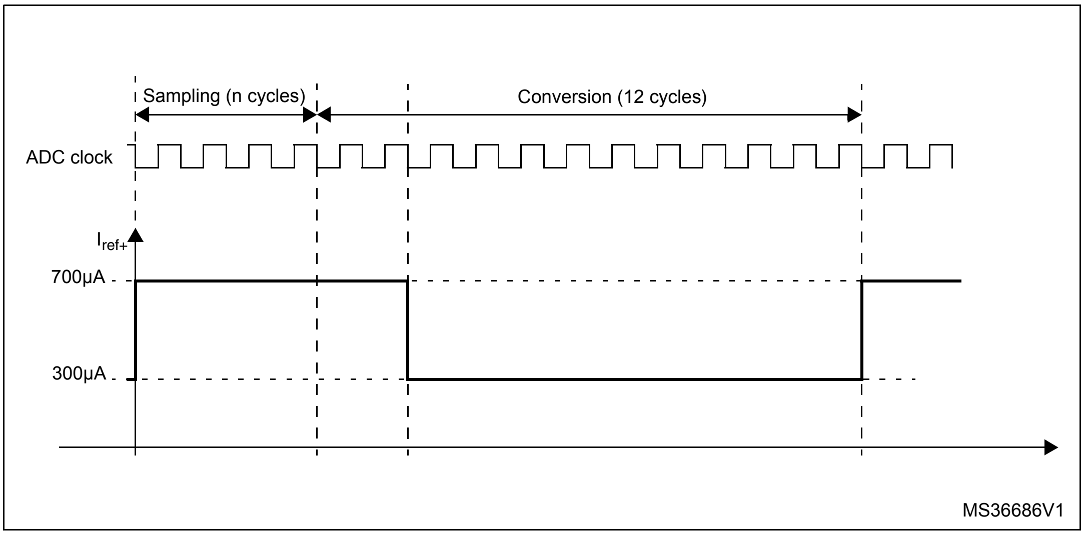


Table 58. Maximum source impedance R_{AIN} max(1)

Ts (µs)	R_{AIN} max (kΩ)				Ts (cycles) f_{ADC}=16 MHz(2)
	Multiplexed channels		Direct channels		
	2.4 V < V_{DDA} < 3.6 V	1.8 V < V_{DDA} < 2.4 V	2.4 V < V_{DDA} < 3.6 V	1.8 V < V_{DDA} < 2.4 V	
0.25	Not allowed	Not allowed	0.7	Not allowed	4
0.5625	0.8	Not allowed	2.0	1.0	9
1	2.0	0.8	4.0	3.0	16
1.5	3.0	1.8	6.0	4.5	24
3	6.8	4.0	15.0	10.0	48
6	15.0	10.0	30.0	20.0	96
12	32.0	25.0	50.0	40.0	192
24	50.0	50.0	50.0	50.0	384

1. Guaranteed by design.
2. Number of samples calculated for f_{ADC} = 16 MHz. For f_{ADC} = 8 and 4 MHz the number of sampling cycles can be reduced with respect to the minimum sampling time Ts (µs),

General PCB design guidelines

Power supply decoupling should be performed as shown in *Figure 12*. The applicable procedure depends on whether V_{REF+} is connected to V_{DDA} or not. The 100 nF capacitors should be ceramic (good quality). They should be placed as close as possible to the chip.

6.3.18 DAC electrical specifications

Data guaranteed by design, unless otherwise specified.

Table 59. DAC characteristics

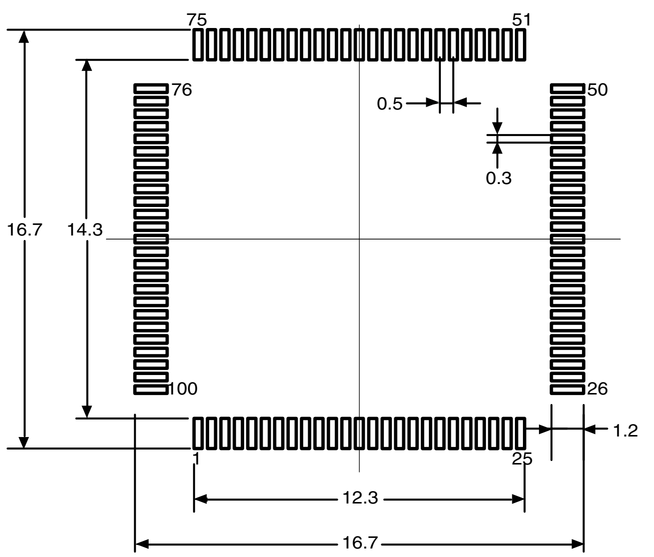
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{DDA}	Analog supply voltage	-	1.8	-	3.6	V
V_{REF+}	Reference supply voltage	V_{REF+} must always be below V_{DDA}	1.8	-	3.6	V
V_{REF-}	Lower reference voltage	-	V_{SSA}			V
$I_{DDVREF+}$(1)	Current consumption on V_{REF+} supply V_{REF+} = 3.3 V	No load, middle code (0x800)	-	130	220	µA
		No load, worst code (0x000)	-	220	350	µA
I_{DDA}(1)	Current consumption on V_{DDA} supply V_{DDA} = 3.3 V	No load, middle code (0x800)	-	210	320	µA
		No load, worst code (0xF1C)	-	320	520	µA
R_L(2)	Resistive load	DAC output buffer ON	5	-	-	kΩ
C_L(2)	Capacitive load	DAC output buffer ON	-	-	50	pF
R_O	Output impedance	DAC output buffer OFF	12	16	20	kΩ
V_{DAC_OUT}	Voltage on DAC_OUT output	DAC output buffer ON	0.2	-	$V_{DDA} - 0.2$	V
		DAC output buffer OFF	0.5	-	V_{REF+} – 1LSB	mV
DNL(1)	Differential non linearity(3)	$C_L \leq 50$ pF, $R_L \geq 5$ kΩ DAC output buffer ON	-	1.5	3	LSB
		No R_L, $C_L \leq 50$ pF DAC output buffer OFF	-	1.5	3	LSB
INL(1)	Integral non linearity(4)	$C_L \leq 50$ pF, $R_L \geq 5$ kΩ DAC output buffer ON	-	2	4	LSB
		No R_L, $C_L \leq 50$ pF DAC output buffer OFF	-	2	4	LSB
Offset(1)	Offset error at code 0x800 (5)	$C_L \leq 50$ pF, $R_L \geq 5$ kΩ DAC output buffer ON	-	±10	±25	LSB
		No R_L, $C_L \leq 50$ pF DAC output buffer OFF	-	±5	±8	LSB
Offset1(1)	Offset error at code 0x001(6)	No R_L, $C_L \leq 50$ pF DAC output buffer OFF	-	±1.5	±5	LSB

Table 66. LQPF100, 14 x 14 mm, 100-pin low-profile quad flat package mechanical data (continued)

Symbol	millimeters			inches[1]		
	Min	Typ	Max	Min	Typ	Max
b	0.170	0.220	0.270	0.0067	0.0087	0.0106
c	0.090	-	0.200	0.0035	-	0.0079
D	15.800	16.000	16.200	0.6220	0.6299	0.6378
D1	13.800	14.000	14.200	0.5433	0.5512	0.5591
D3	-	12.000	-	-	0.4724	-
E	15.800	16.000	16.200	0.6220	0.6299	0.6378
E1	13.800	14.000	14.200	0.5433	0.5512	0.5591
E3	-	12.000	-	-	0.4724	-
e	-	0.500	-	-	0.0197	-
L	0.450	0.600	0.750	0.0177	0.0236	0.0295
L1	-	1.000	-	-	0.0394	-
k	0.0°	3.5°	7.0°	0.0°	3.5°	7.0°
ccc	-	-	0.080	-	-	0.0031

1. Values in inches are converted from mm and rounded to 4 decimal digits.

Figure 33. LQFP100, 14 x 14 mm, 100-pin low-profile quad flat package recommended footprint



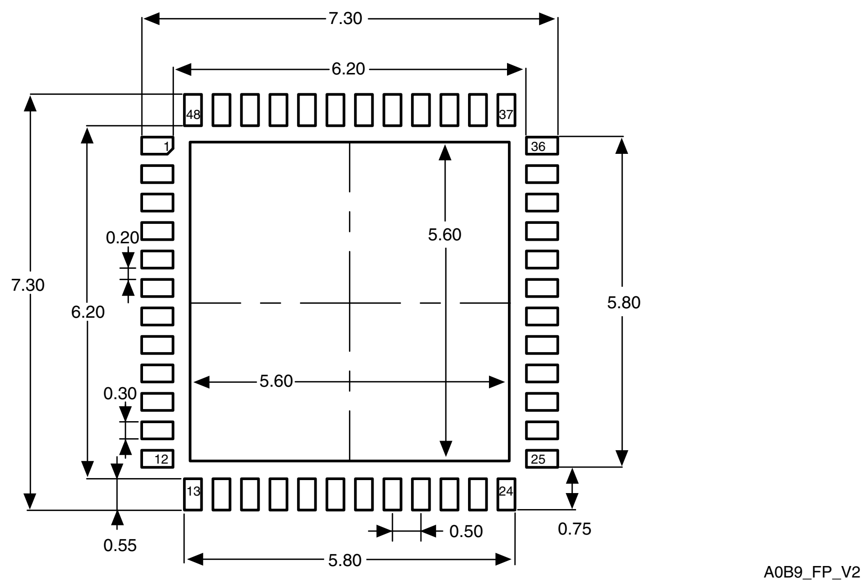
1. Dimensions are in millimeters.

Table 69. UFQFPN48 – ultra thin fine pitch quad flat pack no-lead 7 × 7 mm, 0.5 mm pitch package mechanical data

Symbol	millimeters			inches[1]		
	Min	Typ	Max	Min	Typ	Max
A	0.500	0.550	0.600	0.0197	0.0217	0.0236
A1	0.000	0.020	0.050	0.0000	0.0008	0.0020
D	6.900	7.000	7.100	0.2717	0.2756	0.2795
E	6.900	7.000	7.100	0.2717	0.2756	0.2795
D2	5.500	5.600	5.700	0.2165	0.2205	0.2244
E2	5.500	5.600	5.700	0.2165	0.2205	0.2244
L	0.300	0.400	0.500	0.0118	0.0157	0.0197
T	-	0.152	-	-	0.0060	-
b	0.200	0.250	0.300	0.0079	0.0098	0.0118
e	-	0.500	-	-	0.0197	-
ddd	-	-	0.080	-	-	0.0031

1. Values in inches are converted from mm and rounded to 4 decimal digits.

Figure 42. UFQFPN48 recommended footprint



1. Dimensions are in millimeters.